

Material Declaration Report



Package Type:	PBGA 256L
Pericom Package Code:	ND256(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	689.430
Termination Plating:	SnAgCu
JESD 97 Pb-free Category:	e1
Plating Thickness (um):	N/A
Tin Whisker Mitigation:	N/A

MSL Rating:	3
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	6/4/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	344.577	ASEM	Silica	60676-86-0	90.000	310.1194
			Epoxy resin	Trade Secret	5.500	18.9517
			Phenol resin	Trade Secret	4.500	15.5060
SUBSTRATE	220.687		Cured resin	Trade Secret	20.000	44.1373
			Inorganic Filler	Trade Secret	20.000	44.1373
			Glass fabric	65997-17-3	25.000	55.1716
			Copper foil	7440-50-8	35.000	77.2403
SILICON DIE	23.027		Silicon (Si)	7440-21-3	99.192	22.8409
			Non-hazardous Metal	Proprietary	0.808	0.1861
DIE ATTACH EPOXY	1.862		Silver	7440-22-4	80.000	1.4892
			Di-ester Resin	Proprietary	10.000	0.1862
			Functionalized ester	Proprietary	6.000	0.1117
			Epoxy Resin	Proprietary	2.000	0.0372
			Polymeric Resin	Proprietary	2.000	0.0372
GOLD WIRE	4.550		Gold(Au)	7440-57-5	99.990	4.5497
			Impurities	-	0.010	0.0005
SOLDER BALL	94.728		Tin(Sn)	7440-31-5	96.500	91.4122
			Silver(Ag)	7440-22-4	3.000	2.8418
			Copper(Cu)	7440-50-8	0.500	0.4736

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Substrate	<2	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Ball	<95	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.